

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

	:	Examiner:	S.J. Cohen
Hans-Jurgen Albrecht, et al.	)		
	:	Group Art No.:	1793
Application No.: 10/554,274	)		
	:	Confirmation No.:	3094
Filed: September 13, 2006	)		
	:		
For: SOLDERING MATERIAL BASED ON Sn	)		
Ag AND Cu	:	April 27, 2010	

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Office Action mailed January 27, 2010, kindly amend the subject application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 4 of this paper.